L Number	Hits	Search Text	DB	Time stamp
-	7	polishing adj pad and duro	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/02 19:23
-	193	polishing adj pad and durometer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/02 19:38
-	67	polishing adj pad same durometer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/02 19:24
-	19	(polishing adj pad and durometer) and pore	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/02 19:24
-	66	(polishing adj pad) near7 micron	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/02 19:50
-	608	(polishing adj pad) near7 thickness	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/02 20:02
-	535	(polishing adj pad) near5 thickness	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/02 19:50
-	370	(polishing adj pad) near3 thickness	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/02 19:50
-	301	(polishing adj pad) near2 thickness	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/02 19:51
-	195	(polishing adj pad) near thickness	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/02 19:51
-	101	(polishing adj pad) near7 thickness near2 layer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/02 19:51
-	16	((polishing adj pad) near7 thickness) and adhesive adj tape	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/02 20:03

C:\APPS\EAST\workspaces\10602477.wsp